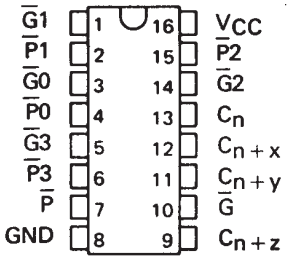
- **Directly Compatible for Use With:**
  SN54LS181/SN74LS181,
  SN54S281/SN74S281, SN54S381,
  SN74S381, SN54S481/SN74S481

PIN DESIGNATIONS

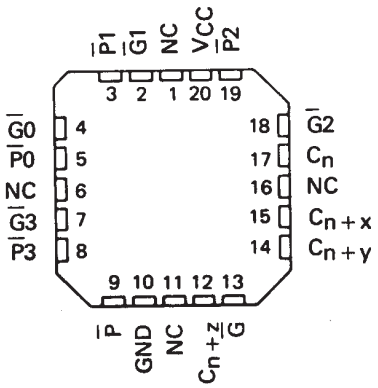
ALTERNATIVE	DESIGNATIONS†	PIN NOS.	FUNCTION
$\overline{G}0, \overline{G}1, \overline{G}2, \overline{G}3$	G0, G1, G2, G3	3, 1, 14, 5	CARRY GENERATE INPUTS
$\overline{P}0, \overline{P}1, \overline{P}2, \overline{P}3$	P0, P1, P2, P3	4, 2, 15, 6	CARRY PROPAGATE INPUTS
C_n	$\overline{C}_n$	13	CARRY INPUT
$C_{n+x}, C_{n+y}, C_{n+z}$	$\overline{C}_{n+x}, \overline{C}_{n+y}, \overline{C}_{n+z}$	12, 11, 9	CARRY OUTPUTS
$\overline{G}$	Y	10	CARRY GENERATE OUTPUT
$\overline{P}$	X	7	CARRY PROPAGATE OUTPUT
V_{CC}		16	SUPPLY VOLTAGE
GND		8	GROUND

†Interpretations are illustrated in the 'LS181, 'S181 data sheet.

SN54S182 . . . J OR W PACKAGE
SN74S182 . . . D OR N PACKAGE
(TOP VIEW)

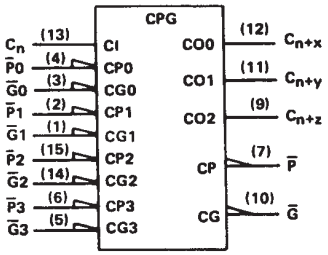


SN54S182 . . . FK PACKAGE
(TOP VIEW)



NC - No internal connection

logic symbol‡



‡This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.
Pin numbers shown are for D, J, N, and W packages.

description

The SN54S182 and SN74S182 are high-speed, look-ahead carry generators capable of anticipating a carry across four binary adders or group of adders. They are cascadable to perform full look-ahead across n-bit adders. Carry, generate-carry, and propagate-carry functions are provided as enumerated in the pin designation table above.

When used in conjunction with the 'LS181 or 'S181 arithmetic logic unit (ALU), these generators provide high-speed carry look-ahead capability for any word length. Each 'S182 generates the look-ahead (anticipated carry) across a group of four ALUs and, in addition, other carry look-ahead circuits may be employed to anticipate carry across sections of four look-ahead packages up to n-bits. The method of cascading 'S182 circuits to perform multilevel look-ahead is illustrated under typical application data.

The carry functions (inputs, outputs, generate, and propagate) of the look-ahead generators are implemented in the compatible forms for direct connection to the ALU. Reinterpretations of carry functions as explained on the 'LS181 and 'S181 data sheet are also applicable to and compatible with the look-ahead generator. Logic equations for the 'S182 are:

$$C_{n+x} = G0 + P0\,C_n$$
$$C_{n+y} = G1 + P1\,G0 + P1\,P0\,C_n$$
$$C_{n+z} = G2 + P2\,G1 + P2\,P1\,G0 + P2\,P1\,P0\,C_n$$
$$\overline{G} = \overline{G3 + P3\,G2 + P3\,P2\,G1 + P3\,P2\,P1\,G0}$$
$$\overline{P} = \overline{P3\,P2\,P1\,P0}$$

or

$$\overline{C}_{n+x} = \overline{Y0\,(X0 + C_n)}$$
$$\overline{C}_{n+y} = \overline{Y1\,[X1 + Y0\,(X0 + C_n)]}$$
$$\overline{C}_{n+z} = \overline{Y2\,\{X2 + Y1\,[X1 + Y0\,(X0 + C_n)]\}}$$
$$Y = Y3\,(X3 + Y2)\,(X3 + X2 + Y1)\,(X3 + X2 + X1 + Y0)$$
$$X = X3 + X2 + X1 + X0$$

FUNCTION TABLE FOR $\overline{G}$ OUTPUT

INPUTS							OUTPUT
$\overline{G}3$	$\overline{G}2$	$\overline{G}1$	$\overline{G}0$	$\overline{P}3$	$\overline{P}2$	$\overline{P}1$	$\overline{G}$
L	X	X	X	X	X	X	L
X	L	X	X	L	X	X	L
X	X	L	X	L	L	X	L
X	X	X	L	L	L	L	L
All other combinations							H

FUNCTION TABLE FOR $\overline{P}$ OUTPUT

INPUTS				OUTPUT
$\overline{P}3$	$\overline{P}2$	$\overline{P}1$	$\overline{P}0$	$\overline{P}$
L	L	L	L	L
All other combinations				H

FUNCTION TABLE FOR C_{n+x} OUTPUT

INPUTS			OUTPUT
$\overline{G}0$	$\overline{P}0$	Cn	C_{n+x}
L	X	X	H
X	L	H	H
All other combinations			L

FUNCTION TABLE FOR C_{n+y} OUTPUT

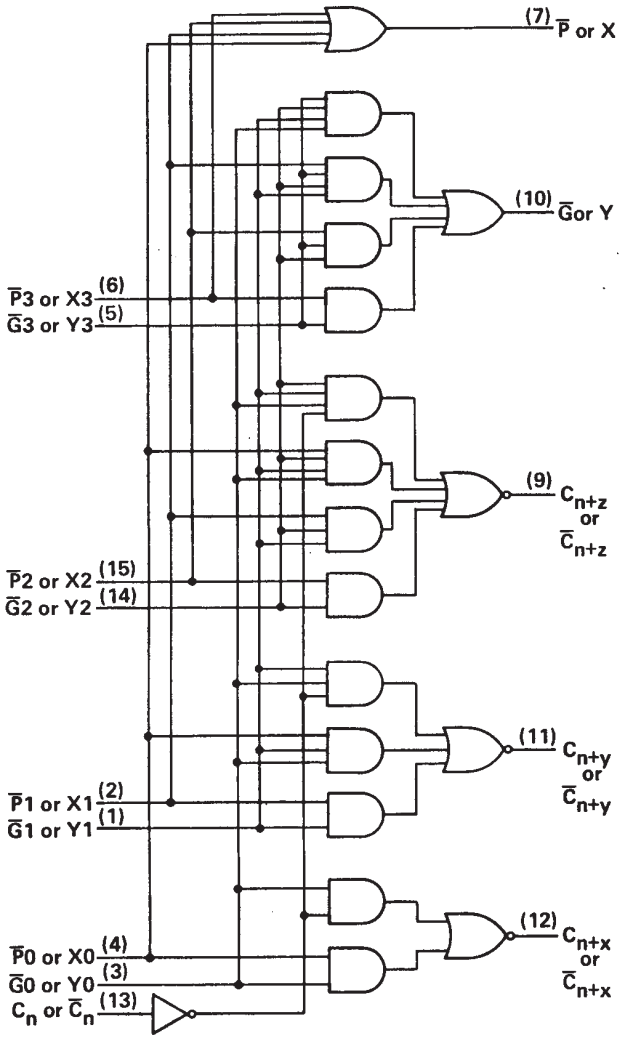
INPUTS					OUTPUT
$\overline{G}1$	$\overline{G}0$	$\overline{P}1$	$\overline{P}0$	C_n	C_{n+y}
L	X	X	X	X	H
X	L	L	X	X	H
X	X	L	L	H	H
All other combinations					L

FUNCTION TABLE FOR C_{n+z} OUTPUT

INPUTS							OUTPUT
$\overline{G}2$	$\overline{G}1$	$\overline{G}0$	$\overline{P}2$	$\overline{P}1$	$\overline{P}0$	C_n	C_{n+z}
L	X	X	X	X	X	X	H
X	L	X	L	X	X	X	H
X	X	L	L	L	X	X	H
X	X	X	L	L	L	H	H
All other combinations							L

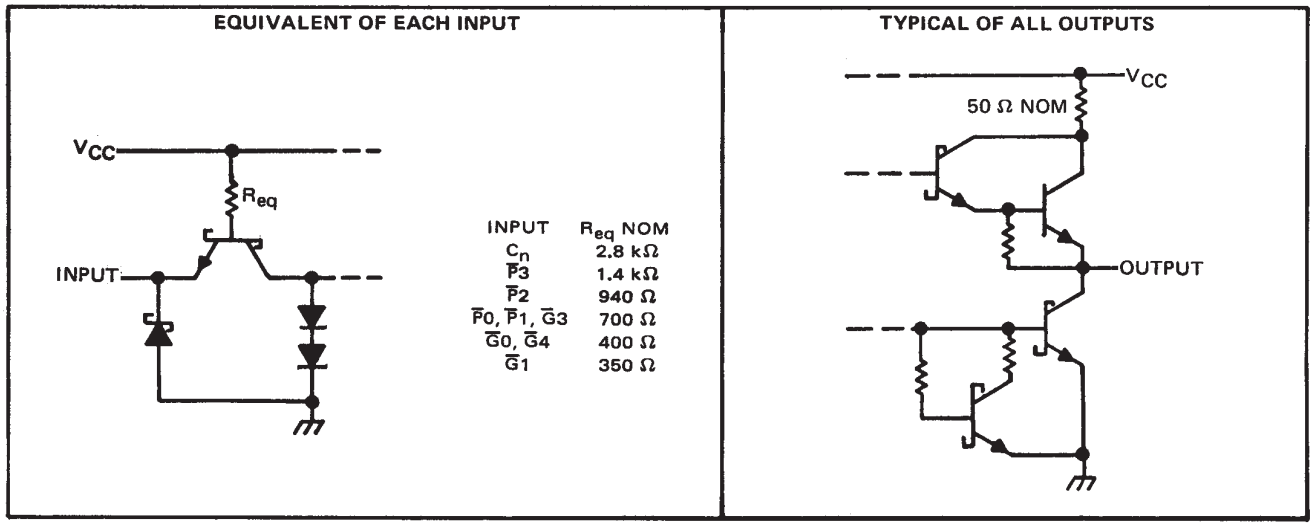
H = high level, L = low level, X = irrelevant
Any inputs not shown in a given table are irrelevant with respect to that output.

logic diagram (positive logic)



Pin numbers shown are for D, J, N, and W packages.

schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage . . . . . 5.5 V
Interemitter voltage (see Note 2) . . . . . 5.5 V
Operating free-air temperature range: SN54S182 . . . . . −55°C to 125°C
SN74S182 . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTES: 1. Voltage values, except interemitter voltage, are with respect to network ground terminal.
2. This is the voltage between two emitters of a multiple-emitter input transistor. For these circuits, this rating applies to each $\overline{G}$ input in conjunction with any other $\overline{G}$ input or in conjunction with any $\overline{P}$ input.

recommended operating conditions

	SN54S182			SN74S182			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}			−1			−1	mA
Low-level output current, I_{OL}			20			20	mA
Operating free-air temperature, T_A	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS†	SN54S182			SN74S182			UNIT
				MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IH}	High-level input voltage			2			2			V
V_{IL}	Low-level input voltage					0.8			0.8	V
V_{IK}	Input clamp voltage		V_{CC} = MIN, I_I = −18 mA			−1.2			−1.2	V
V_{OH}	High-level output voltage		V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = 0.8 V, I_{OH} = −1 mA	2.5	3.4		2.7	3.4		V
V_{OL}	Low-level output voltage		V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = 0.8 V, I_{OL} = 20 mA			0.5			0.5	V
I_I	Input current at maximum input voltage		V_{CC} = MAX, V_I = 5.5 V			1			1	mA
I_{IH}	High-level input current	C_n input	V_{CC} = MAX, V_I = 2.7 V			50			50	μA
		$\overline{P}3$ input				100			100	
		$\overline{P}2$ input				150			150	
		$\overline{P}0$, $\overline{P}1$, or $\overline{G}3$ input				200			200	
		$\overline{G}0$ or $\overline{G}2$ input				350			350	
		$\overline{G}1$ input				400			400	
I_{IL}	Low-level input current	C_n input	V_{CC} = MAX, V_I = 0.5 V			−2			−2	mA
		$\overline{P}3$ input				−4			−4	
		$\overline{P}2$ input				−6			−6	
		$\overline{P}0$, $\overline{P}1$, or $\overline{G}3$ input				−8			−8	
		$\overline{G}0$ or $\overline{G}2$ input				−14			−14	
		$\overline{G}1$ input				−16			−16	
I_{OS}	Short-circuit output current§		V_{CC} = MAX	−40		−100	−40		−100	mA
I_{CCH}	Supply current, all outputs high		V_{CC} = 5 V, See Note 3		35	65		35	70	mA
I_{CCL}	Supply current, all outputs low		V_{CC} = MAX, See Note 4		69	99		69	109	mA

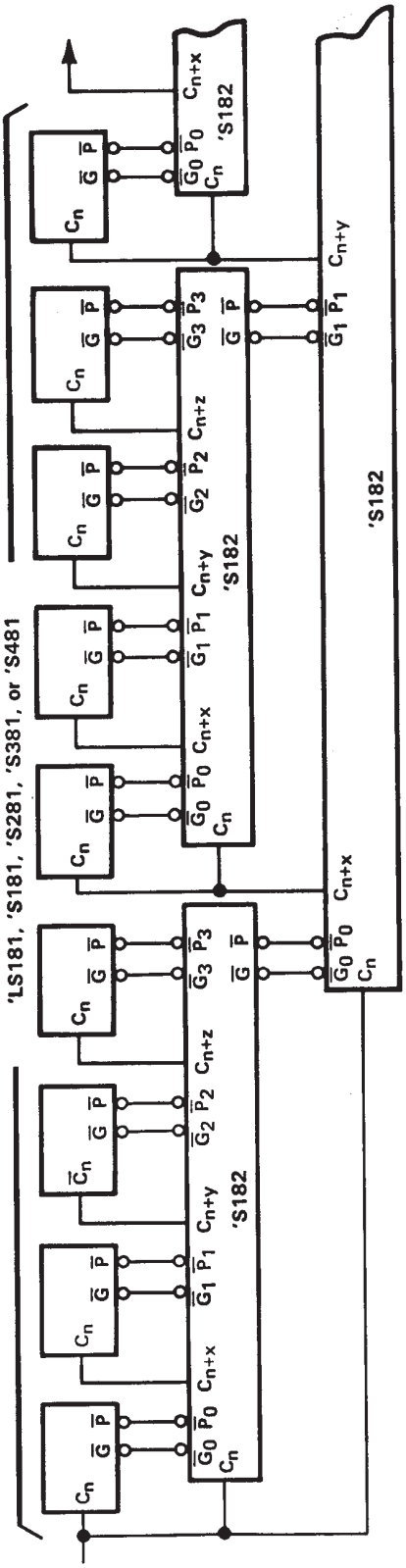
† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ Not more than one output should be shorted at a time and duration of the short-circuit test should not exceed one second.
NOTES: 3. I_{CCH} is measured with all outputs open, inputs $\overline{P}3$ and $\overline{G}3$ at 4.5 V, and all other inputs grounded. MAX is determined at 5.5 V.
4. I_{CCL} is measured with all outputs open; inputs $\overline{G}0$, $\overline{G}1$, and $\overline{G}2$ at 4.5 V; and all other inputs grounded.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	$\overline{G}0$, $\overline{G}1$, $\overline{G}2$, $\overline{G}3$, P0, P1, P2, or P3	C_{n+x}, C_{n+y}, or C_{n+z}	R_L = 280 Ω, C_L = 15 pF, See Note 5		4.5	7	ns
t_{PHL}					4.5	7	
t_{PLH}	$\overline{G}0$, $\overline{G}1$, $\overline{G}2$, $\overline{G}3$, P1, P2, or P3	$\overline{G}$			5	7.5	ns
t_{PHL}					7	10.5	
t_{PLH}	$\overline{P}0$, $\overline{P}1$, $\overline{P}2$, or $\overline{P}3$	$\overline{P}$			4.5	6.5	ns
t_{PHL}					6.5	10	
t_{PLH}	C_n	C_{n+x}, C_{n+y}, or C_{n+z}			6.5	10	ns
t_{PHL}					7	10.5	

NOTE 5: Load circuits and voltage waveforms are shown in Section 1.

TYPICAL APPLICATION DATA



64-BIT ALU, FULL-CARRY LOOK-AHEAD IN THREE LEVELS

Remaining inputs and outputs of 'LS181, 'S181, 'S281, 'S381, and 'S481 are not shown.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/07802BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07802BEA	Samples
M38510/07802BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07802BEA	Samples
SN54S182J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54S182J	Samples
SN74S182N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74S182N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SNJ54S182FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54S 182FK	Samples
SNJ54S182J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S182J	Samples
SNJ54S182W	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI	-55 to 125	SNJ54S182W	

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

OTHER QUALIFIED VERSIONS OF SN54S182, SN74S182 :

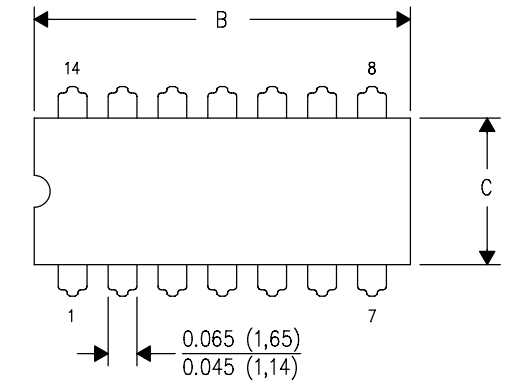
- Catalog: SN74S182
- Military: SN54S182

NOTE: Qualified Version Definitions:

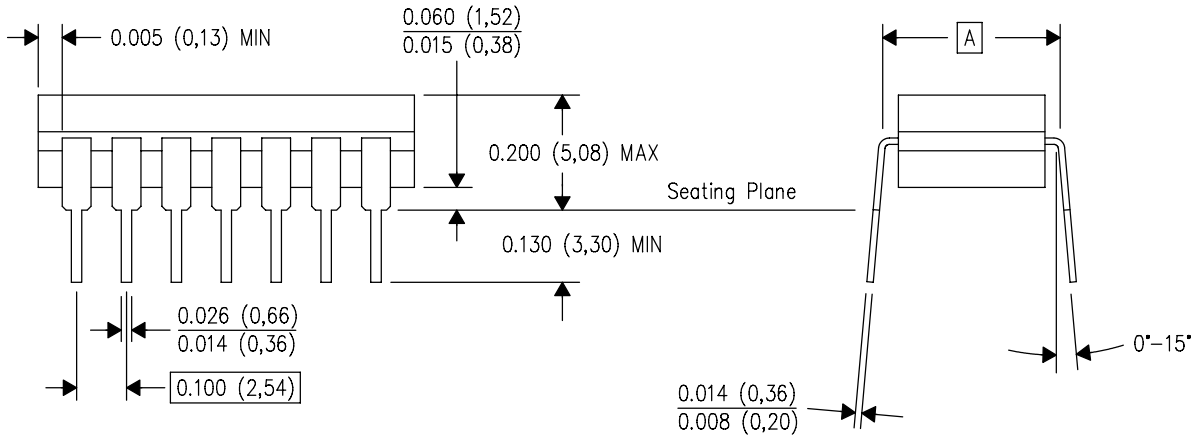
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

J (R–GDIP–T**) CERAMIC DUAL IN–LINE PACKAGE

14 LEADS SHOWN



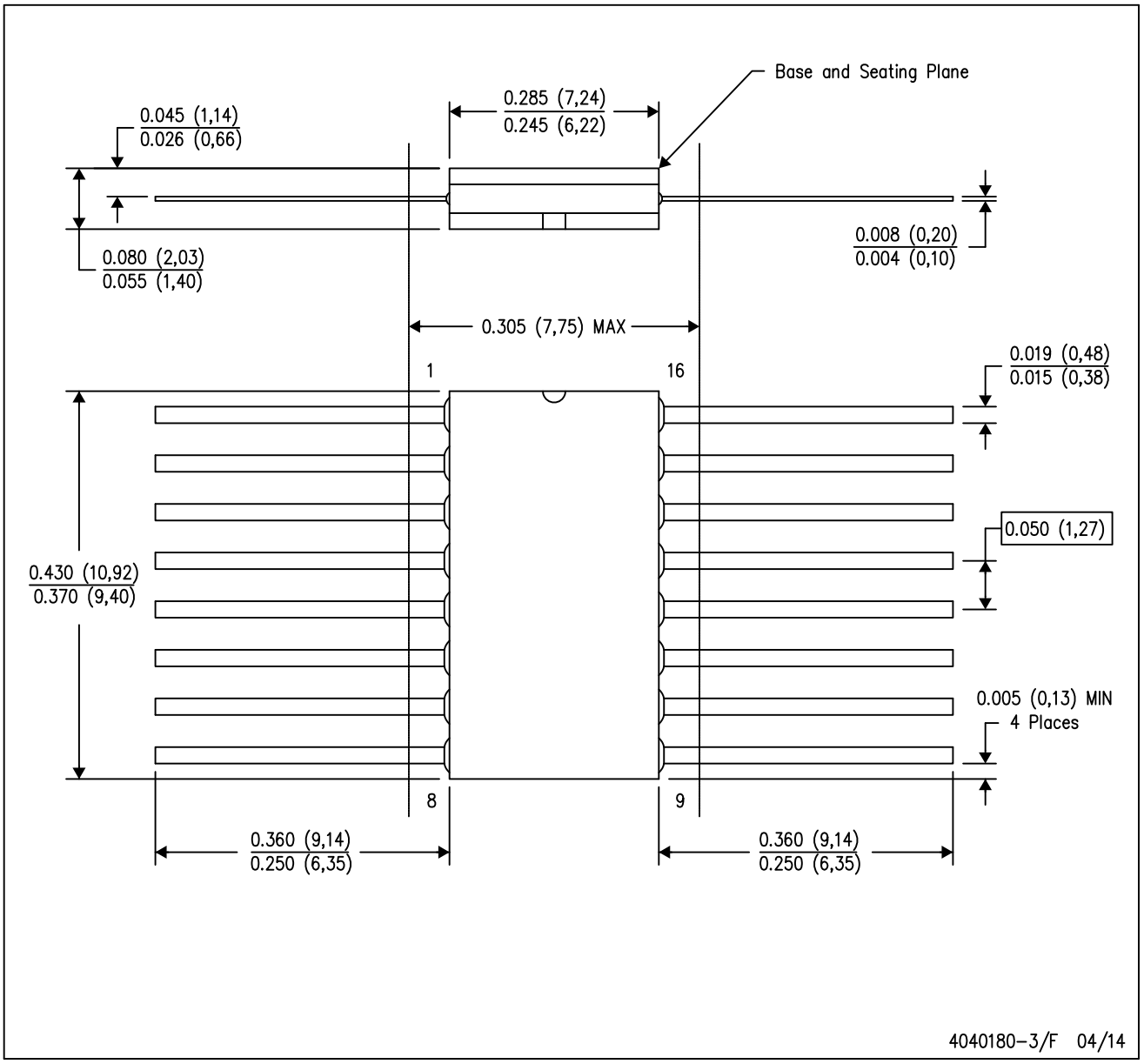
DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

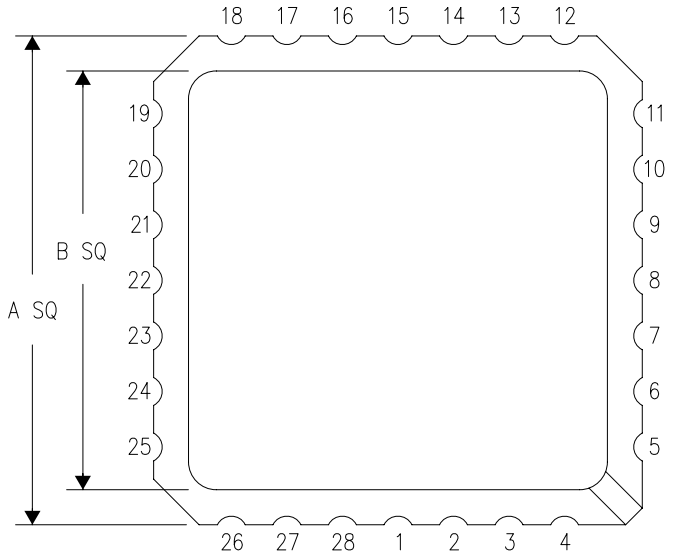
W (R–GDFP–F16) CERAMIC DUAL FLATPACK



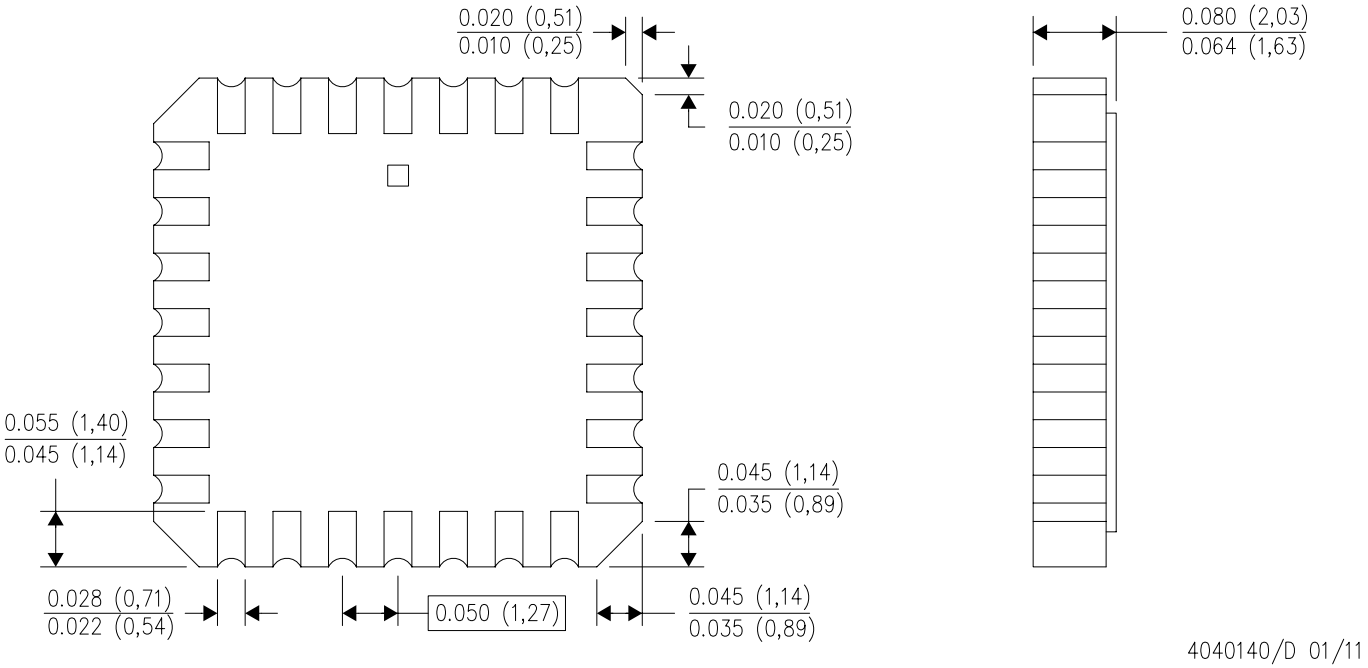
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP2–F16

FK (S–CQCC–N**) LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



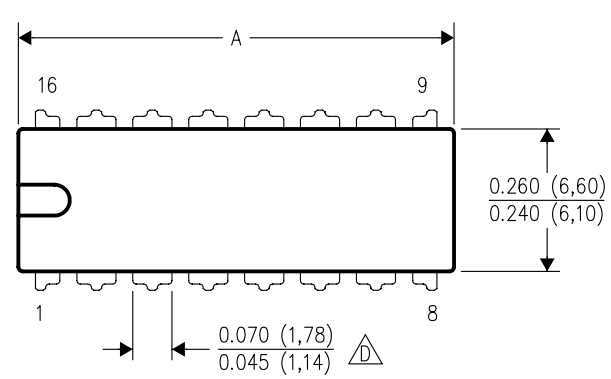
4040140/D 01/11

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. Falls within JEDEC MS–004

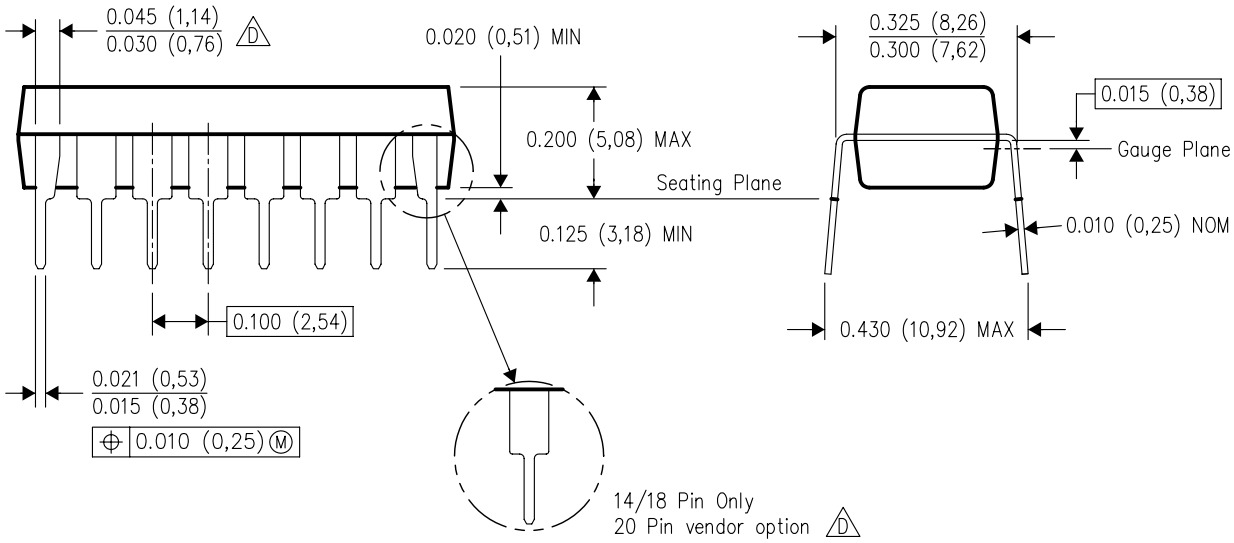
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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